

Title (en)

ELECTRIC COMPONENT, METHOD FOR THE PRODUCTION THEREOF AND USE OF THE SAME

Title (de)

ELEKTRISCHES BAUELEMENT, VERFAHREN ZU DESSEN HERSTELLUNG UND DESSEN VERWENDUNG

Title (fr)

COMPOSANT ELECTRIQUE, SON PROCEDE DE FABRICATION ET SON UTILISATION

Publication

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Application

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Abstract (en)

[origin: WO0182314A1] The invention relates to an electric component comprising a base body (1) that has a stack of electrically conductive electrode layers (3) which overlap one another and which are separated from one another by electrically conductive ceramic layers (10). Said electrically conductive ceramic layers (10) consist of a ceramic, whose specific electric resistance has a negative temperature coefficient. The electrically conductive ceramic layers (10) are produced from ceramic green films that are sintered together with the electrode layers (3). Peripheral electrodes (2), which are connected to the electrode layers (3) in an electrically conductive manner, are positioned on two opposing peripheral faces of the base body (1). The invention also relates to a method for producing the component and to the use of the same.

IPC 8 full level

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